


Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

Materials:

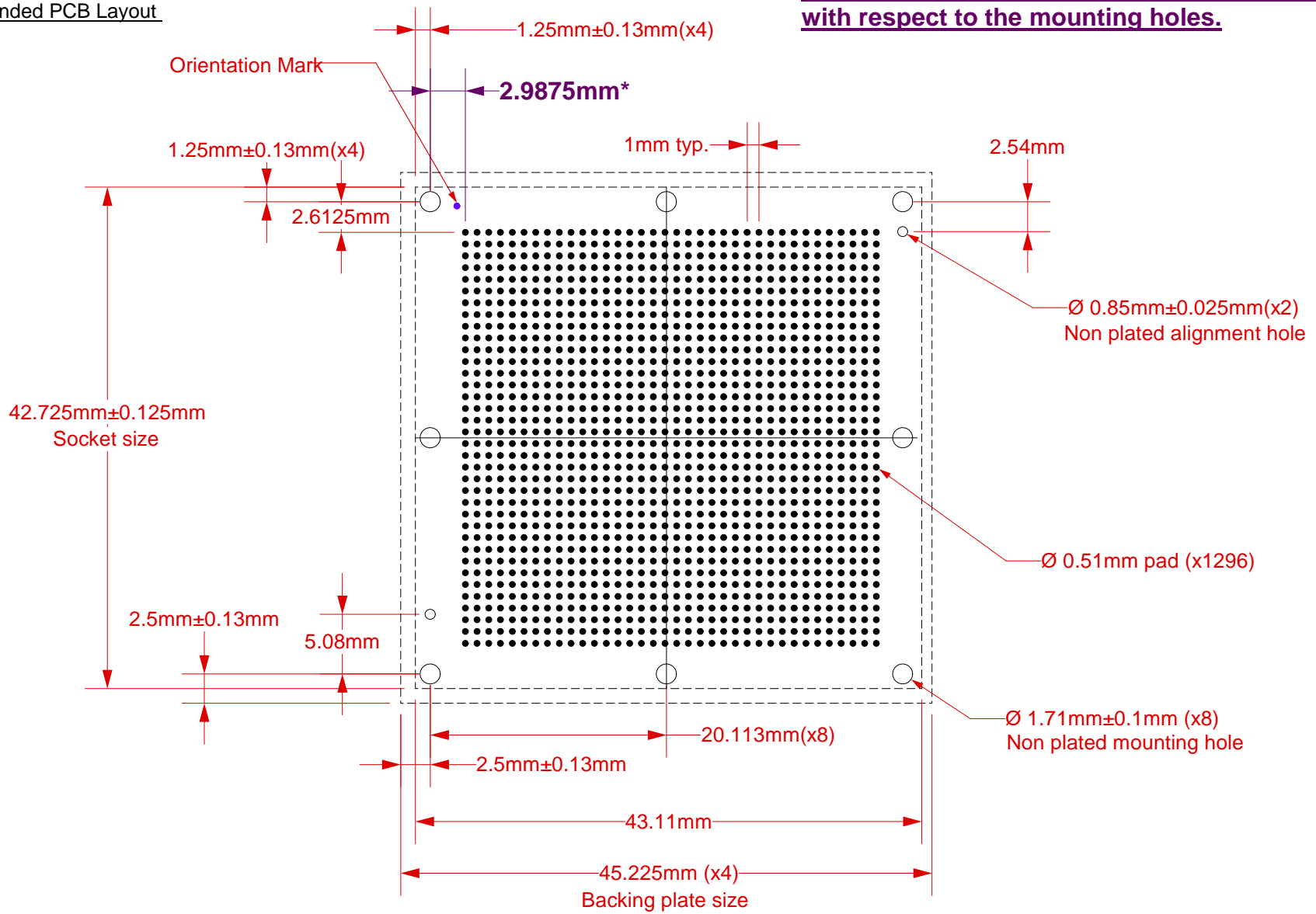
- △1 Clam Shell Lid: Black anodized Aluminum. Height = 20 mm.
- △2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- △3 Compression Plate: Black anodized Aluminum. Thickness = 12 mm.
- △4 Compression Screw: Clear anodized Aluminum. Height = 27 mm, Fluted Knob
- △5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- △6 Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
- △7 Socket Base Screw: Socket Head Cap Screw, Black Oxide, 0-80 Thread, 5/8" long.
- △8 Backing Plate: 6.35mm thick stainless steel
- △9 Insulation Plate: FR4/G10
- △10 Ball Guide: Kapton polyimide.
- △11 Latch: Black anodized Aluminum.

	CG-BGA-4012 Drawing	Status: Released	Scale: -	Rev: A
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		File: CG-BGA-4012 Dwg		Modified:

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

***Note: BGA pattern is shifted to the right by 0.375mm with respect to the mounting holes.**




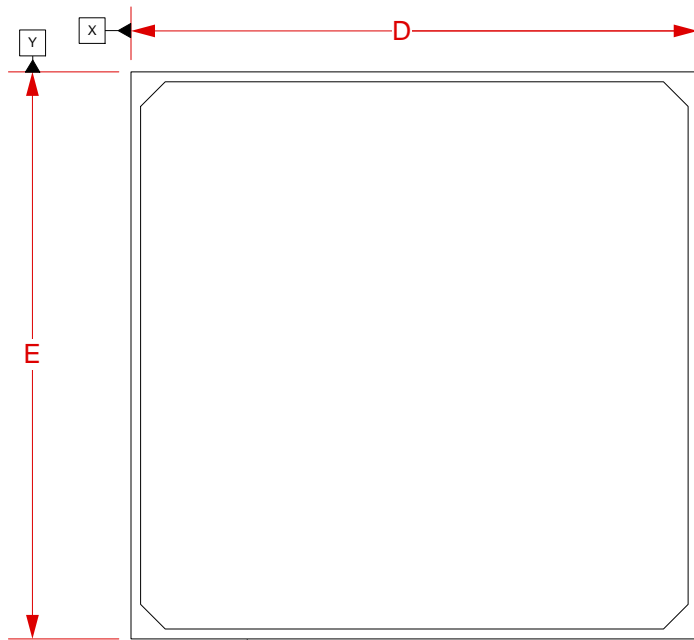
Target PCB Recommendations

Total thickness: 2.4mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

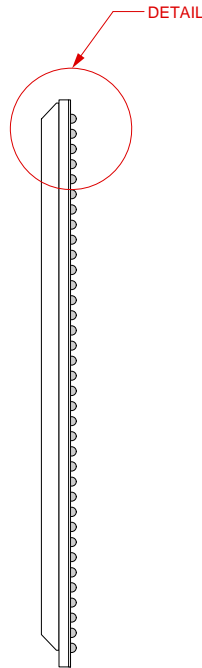
NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

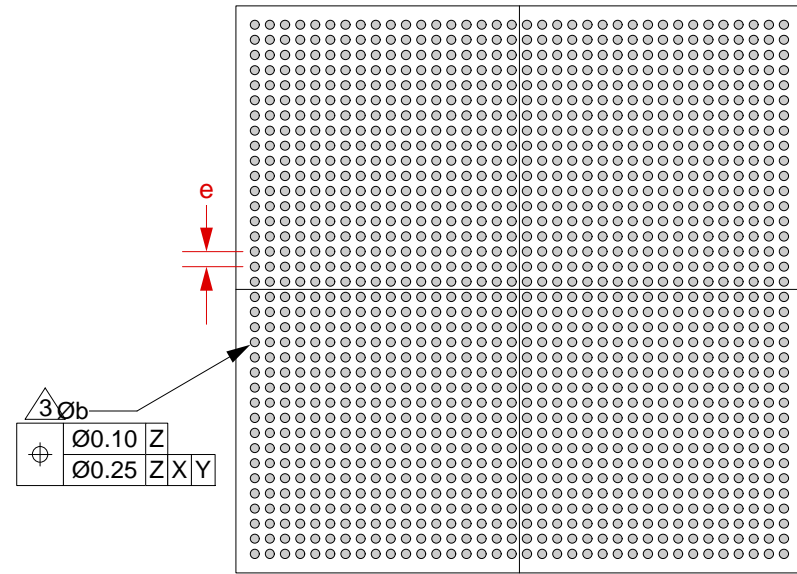
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TOP VIEW

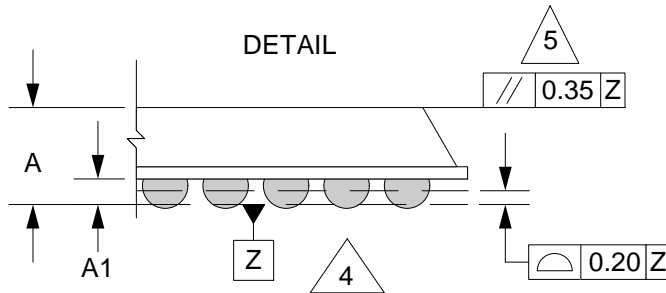


SIDE VIEW



BOTTOM VIEW


0.20



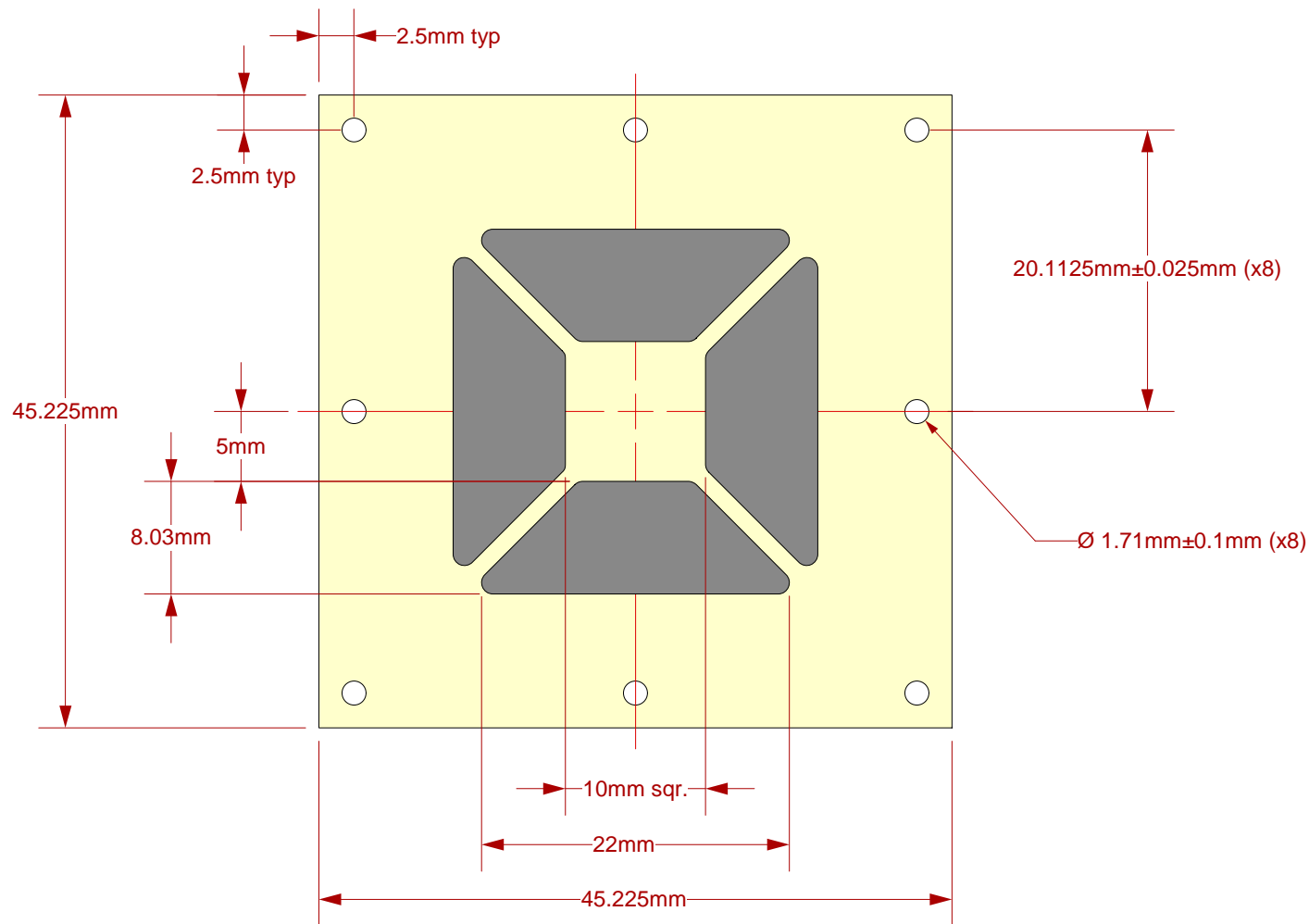
1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.63
A1	0.4	0.6
b		0.7
D	37.50 BSC	
E	37.50 BSC	
e	1.0 BSC	

Array: 36x36

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Top View




Note: Backing plate holes are tapped to accept 0-80 screws.

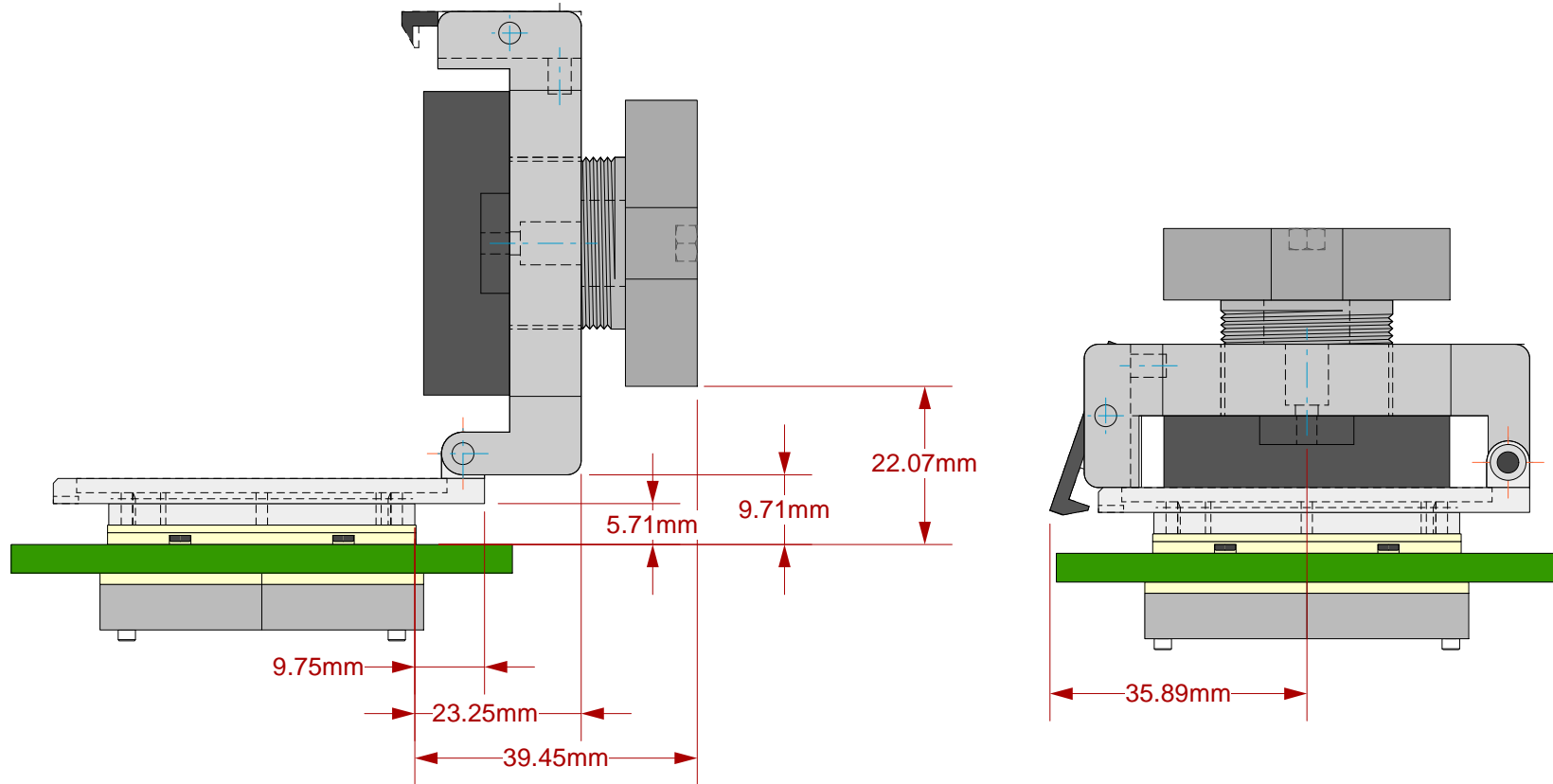
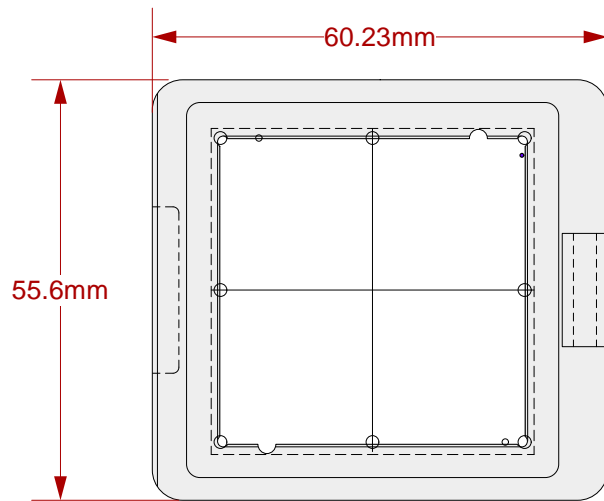
Side View




Description: Backing Plate with Insulation Plate

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)

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All dimensions are in mm.
 All tolerances are +/- 0.125mm.
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